

TECHNIQUES FOR MOUNTING AN AREA ARRAY PACKAGE TO  
A CIRCUIT BOARD USING AN IMPROVED PAD LAYOUT

ABSTRACT OF THE DISCLOSURE

5        A circuit board assembly includes a printed circuit board (PCB). The PCB has a pad layout which includes a set of pads arranged in a two-dimensional array having at least two pads in a first direction and at least two pads in a second direction that is substantially perpendicular to the first direction. Each pad has (i) a central portion and (ii) multiple lobe portions integrated with the central portion and extending from the 10 central portion of that pad. The circuit board assembly further includes a circuit board component mounted to the pad layout via a set of solder joints. The above-described pad layout (or land pattern) is well-suited for soldering to a variety of AAP devices (e.g., either a CCGA device or a BGA device).